

Title (en)

DEPOSITION OF METAL IONS ONTO SURFACES OF CONDUCTIVE SUBSTRATES

Title (de)

ABSCHEIDUNG VON METALLIONEN AUF OBERFLÄCHEN LEITENDER SUBSTRATE

Title (fr)

DÉPÔT D'IONS MÉTALLIQUES SUR DES SURFACES DE SUBSTRATS CONDUCTEURS

Publication

EP 2155927 A4 20160113 (EN)

Application

EP 08770009 A 20080603

Priority

- US 2008065602 W 20080603
- US 93324207 P 20070605
- US 2550608 A 20080204

Abstract (en)

[origin: WO2008151173A1] The present invention provides compositions and processes for preparing metallic ions for deposition on and/or into conductive substrates, such as metals, to substantially eliminate friction from metal to metal contact. It is used in the aqueous embodiment to form new metal surfaces on all metal substrates. The processes form stable aqueous solutions of metal and metalloid ions that can be adsorbed or absorbed on and/or into conductive substrates. The aqueous solutions consist of ammonium alkali metal phosphate salts, and/or ammonium alkali metal sulfate salts mixed with a water soluble metal or metalloid salt from Group I through Group VIII of the periodic table of elements. The aqueous solutions allow for a nano deposition of the metal ions on and/or into the surfaces of conductive substrates. The surfaces created by the deposited metal ions will provide metal passivation and substantially eliminate friction in metal-to-metal contact without the use of hydrocarbon based lubricants.

IPC 8 full level

C23C 22/00 (2006.01); **C23C 18/00** (2006.01); **C23C 22/03** (2006.01); **C23C 22/05** (2006.01); **C23C 22/08** (2006.01); **C23C 22/42** (2006.01)

CPC (source: EP US)

C23C 18/00 (2013.01 - EP US); **C23C 22/03** (2013.01 - EP US); **C23C 22/05** (2013.01 - EP US); **C23C 22/08** (2013.01 - EP US); **C23C 22/42** (2013.01 - EP US)

Citation (search report)

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- [X] US 5540788 A 19960730 - DEFALCO FRANK G [US], et al
- [A] WO 2005120722 A2 20051222 - PIGMENTAN ANTICORROSIVE PIGMEN [IL], et al
- See references of WO 2008151173A1

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MT NL NO PL PT RO SE SI SK TR

DOCDB simple family (publication)

WO 2008151173 A1 20081211; AU 2008259858 A1 20081211; AU 2008259858 B2 20130124; BR PI0811366 A2 20150623; CA 2689437 A1 20081211; CN 101730756 A 20100609; EP 2155927 A1 20100224; EP 2155927 A4 20160113; JP 2010529299 A 20100826; JP 2014159643 A 20140904; JP 5722032 B2 20150520; JP 5926317 B2 20160525; KR 101506360 B1 20150326; KR 20100040832 A 20100421; MX 2009013100 A 20100818; RU 2009145641 A 20110720; RU 2486284 C2 20130627; US 2008302267 A1 20081211

DOCDB simple family (application)

US 2008065602 W 20080603; AU 2008259858 A 20080603; BR PI0811366 A 20080603; CA 2689437 A 20080603; CN 200880023345 A 20080603; EP 08770009 A 20080603; JP 2010511270 A 20080603; JP 2014095173 A 20140502; KR 20107000045 A 20080603; MX 2009013100 A 20080603; RU 2009145641 A 20080603; US 2550608 A 20080204